Atty Docket No.:

275701US6

FORM PTO-1595 06-04

09-27-2005



U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

103089311 To the Director of the United States P. e attached original documents or copy thereof. 1. Name of conveying party(ies): 2. Name and address of receiving party(ies): Yusuke SAKAI SONY CORPORATION Name: Mikio KAMADA Address: 7-35 Kitashinagawa 6-chome, Shinagawa-Ku, Naoki SAITO Tokyo, 141-0001 Japan Additional name(s) of conveying party(ies) attached?

Yes No 3. Nature of Conveyance: Assignment ☐ Merger ☐ Security Agreement ☐ Change of Name ☐ Other Execution Date: September 2, 3, 5, 2005 Additional name(s) and address(es) attached?

Yes No 4. Application number(s) or patent number(s): ☐ This document is being filed together with a new application A. Patent Application No.(s) B. Patent No.(s) 11/188,837 Additional numbers attached?

Yes No 5. Name and address of party to whom correspondence 6. Total applications and patents involved: 1 concerning document should be mailed: 7. Total fee (37 CFR 3.41): \$40.00 Customer Number Enclosed ☐ Authorized to be charged to deposit account Tel. (703) 413-3000 8. Deposit account number: 15-0030 Fax. (703) 413-2220 (Attach duplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE 9. Statement and signature To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. SEP 2 1 2005 Bradley D. Lytle Name of Person Signing Joseph Scafetta, Jr. Registration Number: 40,073 Registration No. 26,803 Total number of pages including this cover sheet: 5 09/23/2005 MBEYENE2 00000207 11188837

01 FC:8021

Do not detach this portion

Mail documents to be recorded with required cover sheet information to:

Director of the United States Patent and Trademark Office Mail Stop Assignment Recordation Services Alexandria, Virginia. 22313

I:\USER\MYAMO\27'\$\275\275701US PTO 1595 FORM.DOC

Docket Number: 275701US6

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

INFORMATION-PROCESSING APPARATUS, INFORMATION-PROCESSING METHODS, RECORDING MEDIUMS, AND PROGRAMS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-chome, Shinagawa-Ku, Tokyo, 141-0001 Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 11/188,837 Filing Date: July 26, 2005.

This assignment executed on the dates indicated below.

Yusuke SAKAI	
Name of first or sole inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	•
Residence of first or sole inventor	
YUSUKE SAKAI	Soptember 2, 2005
Signature of first or sole inventor	Date of this assignment

Mikio KAMADA	
Name of second inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of second inventor	
Mikio Kamada	September3, 2005
Signature of second inventor	Date of this assignment
Naoki SAITO	
Name of third inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of third inventor	
Signature of third inventor	Date of this assignment
8	Date of this assignment

Docket Number: 275701US6

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

INFORMATION-PROCESSING APPARATUS, INFORMATION-PROCESSING METHODS, RECORDING MEDIUMS, AND PROGRAMS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-chome, Shinagawa-Ku, Tokyo, 141-0001 Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 11/188,837 Filing Date: July 26, 2005.

This assignment executed on the dates indicated below.

Yusuke SAKAI	
Name of first or sole inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of first or sole inventor	
Signature of first or sole inventor	Date of this assignment

Mikio KAMADA	
Name of second inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of second inventor	
Signature of second inventor	Date of this assignment
Naoki SAITO	
Name of third inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of third inventor	
Maoki Saito	September 5, 2005
Signature of third inventor	Date of this assignment

RECORDED: 09/21/2005